

PCN Number:	20200210001	PCN Date:	Feb 18, 2020
Title:	Datasheet for AMC1100		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



AMC1100

SBAS562B – APRIL 2012 – REVISED DECEMBER 2019

Changes from Revision A (December 2014) to Revision B	Page
• Changed certification details as per ISO standard in <i>safety-related certifications</i> Features bullet	1
• Deleted typical life span Features bullet	1
• Changed <i>Applications</i> section to include end equipment links	1
• Changed <i>IEC60747-5-2 to DIN VDE V 0884-11: 2017-01</i> in <i>Description</i> section	1
• Changed page 1 figure and added title	1
• Added <i>Power Ratings</i> table	4
• Changed <i>Insulation Specifications</i> table per ISO standard	5
• Added DWV-package related details in <i>Insulation Specifications</i> table	5
• Changed <i>Safety-Related Certification</i> table per ISO standard	6
• Changed <i>Safety Limiting Values</i> table per ISO standard	6
• Deleted VDD1 and VDD2 from <i>Electrical Characteristics</i> table (repeated in <i>Recommended Operating Conditions</i> table)	7
• Added <i>Insulation Characteristics Curves</i> section	8
• Changed <i>Zener Diode Based High-Side Supply</i> figure	21

The datasheet number will be changing.

Device Family	Change From:	Change To:
AMC1100	SBAS562A	SBAS562B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/productAMC1100>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

AMC1100DUB	AMC1100DUBR	AMC1100DWV	AMC1100DWVR
------------	-------------	------------	-------------

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com

Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.